

## 1. General description

High voltage high speed planar passivated NPN power switching transistor in a SOT428 (DPAK) surface mountable plastic package.

## 2. Features and benefits

- Fast switching
- Low thermal resistance
- Surface mountable package
- Tight DC gain spreads
- Very high voltage capability
- Very low switching and conduction losses

## 3. Applications

- DC-to-DC converters
- High frequency electronic lighting ballasts
- Inverters
- Motor control systems

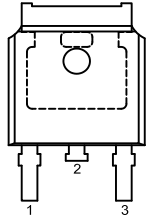
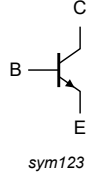
## 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CM}$	peak collector current	<a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	-	10	A
$P_{tot}$	total power dissipation	$T_{mb} \leq 25\text{ °C}$ ; <a href="#">Fig. 4</a>	-	-	80	W
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$	-	-	1050	V
<b>Static characteristics</b>						
$h_{FE}$	DC current gain	$I_C = 10\text{ mA}$ ; $V_{CE} = 3\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 12</a>	28	34	47	
		$I_C = 250\text{ mA}$ ; $V_{CE} = 3\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 12</a>	35	43	57	
		$I_C = 800\text{ mA}$ ; $V_{CE} = 3\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; <a href="#">Fig. 12</a>	31	37	48	

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 <p><b>DPAK (SOT428)</b></p>	 <p>sym123</p>
2	C	collector <sup>[1]</sup>		
3	E	emitter		
mb	C	mounting base; connected to collector		

[1] it is not possible to make a connection to pin 2 of the SOT428 (DPAK) package.

## 6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUJ303CD	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

## 7. Marking

Table 4. Marking codes

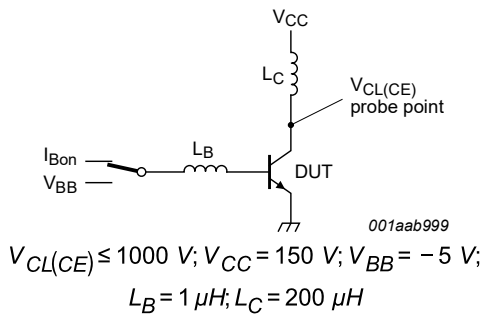
Type number	Marking code
BUJ303CD	BUJ303CD

## 8. Limiting values

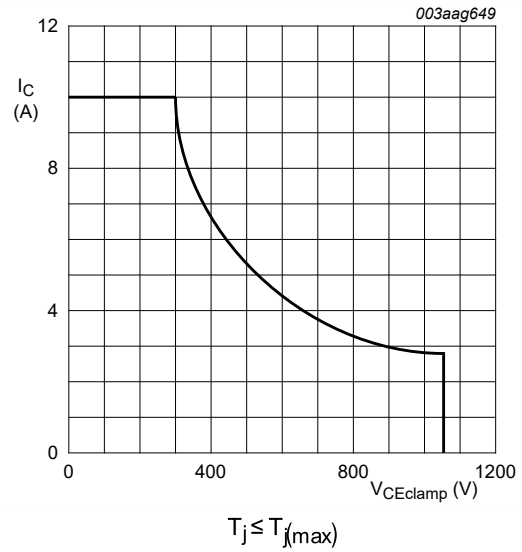
**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

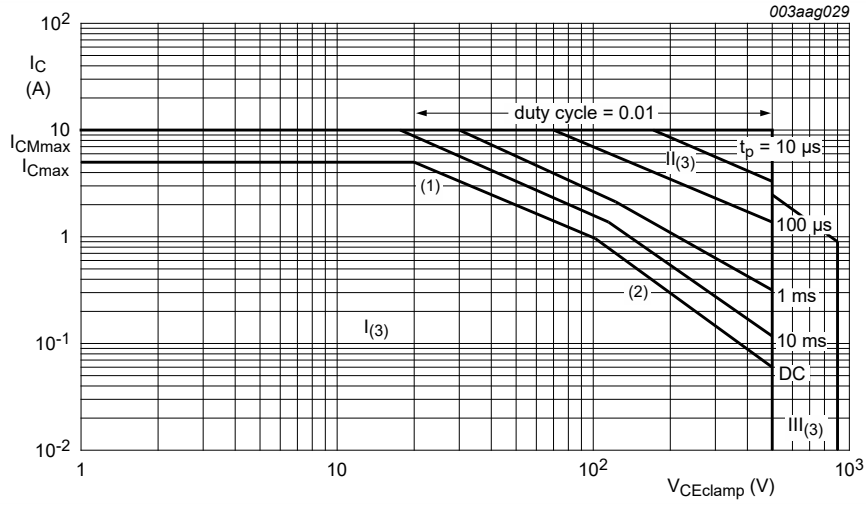
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CESM}$	collector-emitter peak voltage	$V_{BE} = 0\text{ V}$	-	1050	V
$V_{CEO}$	collector-emitter voltage	$I_B = 0\text{ A}$	-	400	V
$I_C$	collector current	<a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	5	A
$I_{CM}$	peak collector current		-	10	A
$I_B$	base current		-	2	A
$I_{BM}$	peak base current		-	4	A
$P_{tot}$	total power dissipation	$T_{mb} \leq 25\text{ °C}$ ; <a href="#">Fig. 4</a>	-	80	W
$T_{stg}$	storage temperature		-65	150	°C
$T_j$	junction temperature		-	150	°C



**Fig. 1. Test circuit for reverse bias safe operating area**

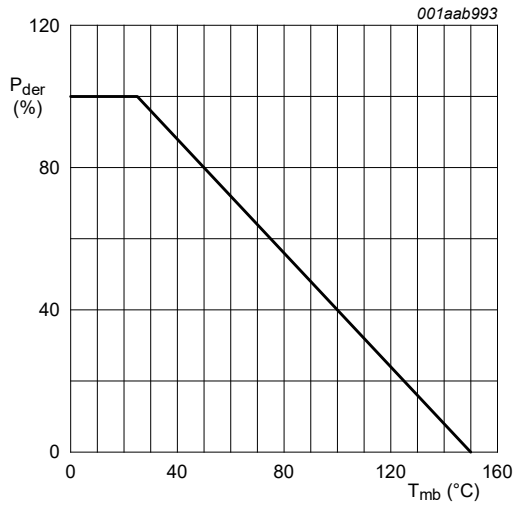


**Fig. 2. Reverse bias safe operating area**



- (1)  $P_{tot}$  maximum and  $P_{tot}$  peak maximum lines.
- (2) Second breakdown limits.
- (3) I = Region of permissible DC operation.
- II = Extension for repetitive pulse operation.
- III = Extension during turn-on in single transistor converters provided that  $R_{BE} \leq 100 \Omega$  and  $t_p \leq 0.6 \mu s$ .

Fig. 3. Forward bias safe operating area for  $T_{mb} \leq 25 \text{ }^\circ\text{C}$



$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ\text{C})}} \times 100 \%$$

Fig. 4. Normalized total power dissipation as a function of mounting base temperature

### 9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	<a href="#">Fig. 5</a>	-	-	1.56	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	printed circuit board (FR4) mounted; minimum footprint; <a href="#">Fig. 6</a>	-	75	-	K/W

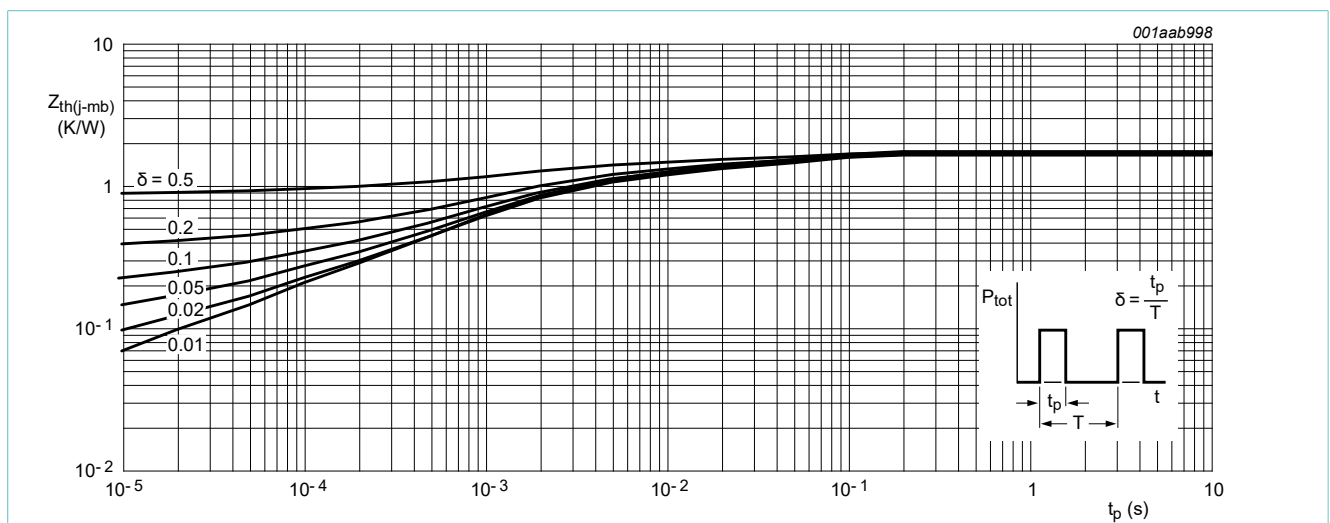


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse width

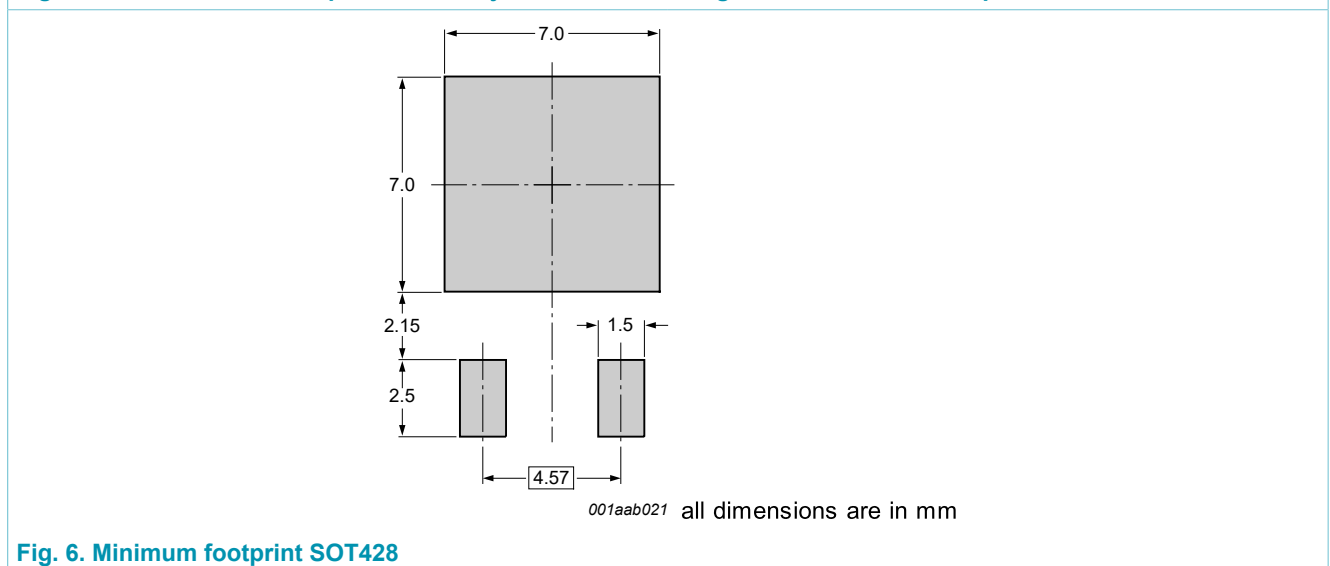


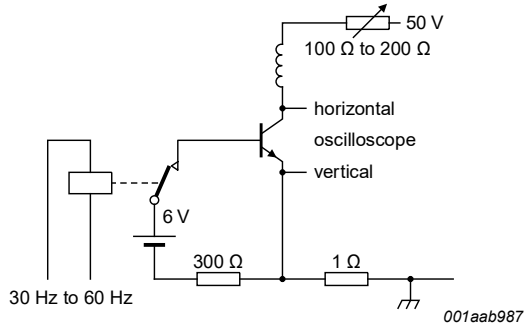
Fig. 6. Minimum footprint SOT428

## 10. Characteristics

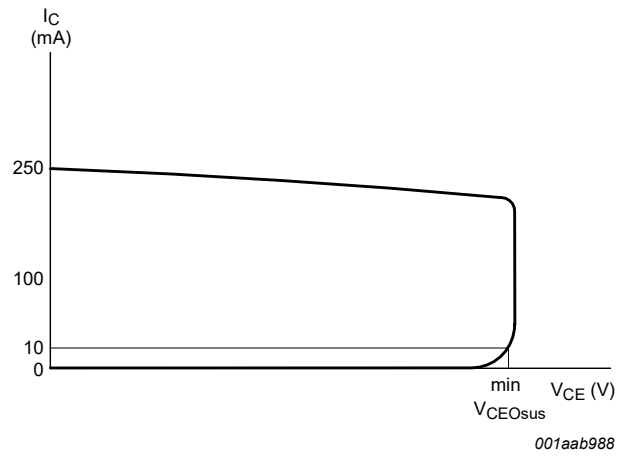
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
<b>Static characteristics</b>							
$I_{CES}$	collector-emitter cut-off current (base shorted)	$V_{BE} = 0\text{ V}; V_{CE} = 1050\text{ V}$	[1]	-	-	1	mA
		$V_{BE} = 0\text{ V}; V_{CE} = 1050\text{ V}; T_j = 125\text{ °C}$	[1]	-	-	2	mA
$I_{CBO}$	collector-base cut-off current (emitter open)	$V_{CB} = 1050\text{ V}; I_E = 0\text{ A}; T_{mb} = 25\text{ °C}$	[1]	-	-	1	mA
$I_{CEO}$	collector-emitter cut-off current (base open)	$V_{CE} = 400\text{ V}; I_B = 0\text{ A}; T_{mb} = 25\text{ °C}$	[1]	-	-	0.1	mA
$I_{EBO}$	emitter-base cut-off current (collector open)	$V_{EB} = 9\text{ V}; I_C = 0\text{ A}; T_{mb} = 25\text{ °C}$	-	-	0.1	mA	
$V_{CEOsus}$	collector-emitter sustaining voltage (base open)	$I_B = 0\text{ A}; I_C = 100\text{ mA}; L_C = 25\text{ mH}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 7</a> ; <a href="#">Fig. 8</a>	400	-	-	V	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 1\text{ A}; I_B = 0.2\text{ A}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 9</a> ; <a href="#">Fig. 10</a>	-	-	0.5	V	
		$I_C = 3\text{ A}; I_B = 1\text{ A}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 9</a> ; <a href="#">Fig. 10</a>	-	0.25	1.5	V	
$V_{BEsat}$	base-emitter saturation voltage	$I_C = 3\text{ A}; I_B = 1\text{ A}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 11</a>	-	1	1.5	V	
$h_{FE}$	DC current gain	$I_C = 10\text{ mA}; V_{CE} = 3\text{ V}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 12</a>	28	34	47		
		$I_C = 250\text{ mA}; V_{CE} = 3\text{ V}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 12</a>	35	43	57		
		$I_C = 800\text{ mA}; V_{CE} = 3\text{ V}; T_{mb} = 25\text{ °C};$ <a href="#">Fig. 12</a>	31	37	48		
<b>Dynamic characteristics (switching times - resistive load)</b>							
$t_{on}$	turn-on time	$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; I_{Boff} = -1\text{ A}; R_L = 100\text{ }\Omega; T_j = 25\text{ °C};$ <a href="#">Fig. 13</a> ; <a href="#">Fig. 14</a>	-	1	-	ms	
$t_s$	storage time		-	2.5	-	ms	
$t_f$	fall time		-	0.3	-	ms	
<b>Dynamic characteristics (switching times - inductive load)</b>							
$t_s$	storage time	$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; V_{BB} = -5\text{ V}; L_B = 1\text{ }\mu\text{H}; T_j = 25\text{ °C};$ <a href="#">Fig. 15</a> ; <a href="#">Fig. 16</a>	-	2	-	ms	
		$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; V_{BB} = -5\text{ V}; L_B = 1\text{ }\mu\text{H}; T_j = 100\text{ °C};$ <a href="#">Fig. 15</a> ; <a href="#">Fig. 16</a>	-	3	-	ms	
$t_f$	fall time	$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; V_{BB} = -5\text{ V}; L_B = 1\text{ }\mu\text{H}; T_j = 25\text{ °C};$ <a href="#">Fig. 15</a> ; <a href="#">Fig. 16</a>	-	200	-	ns	
		$I_C = 2.5\text{ A}; I_{Bon} = 0.5\text{ A}; V_{BB} = -5\text{ V}; L_B = 1\text{ }\mu\text{H}; T_j = 100\text{ °C};$ <a href="#">Fig. 15</a> ; <a href="#">Fig. 16</a>	-	300	-	ns	

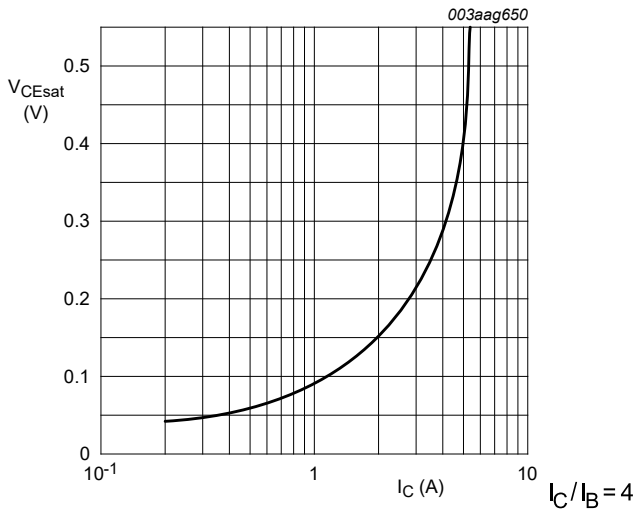
[1] Measured with half-sine wave voltage (curve tracer).



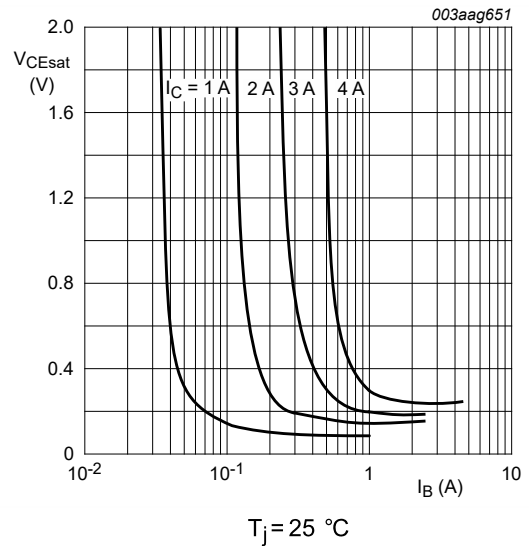
**Fig. 7. Test circuit for collector-emitter sustaining voltage**



**Fig. 8. Oscilloscope display for collector-emitter sustaining voltage test waveform**



**Fig. 9. Collector-emitter saturation voltage as a function of collector current; typical values**



**Fig. 10. Collector-emitter saturation voltage as a function of base current; typical values**

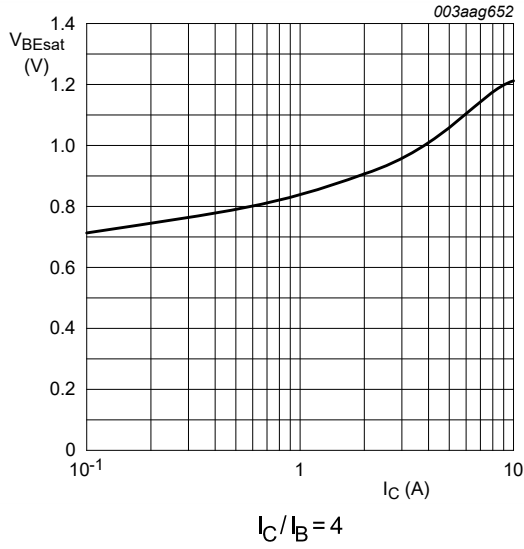


Fig. 11. Base-emitter saturation voltage as a function of collector current; typical values

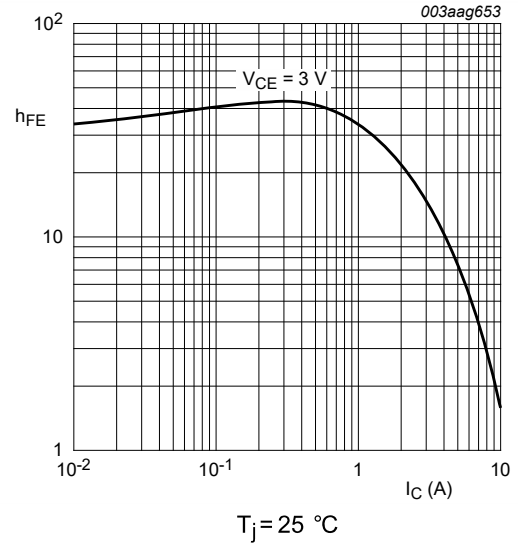
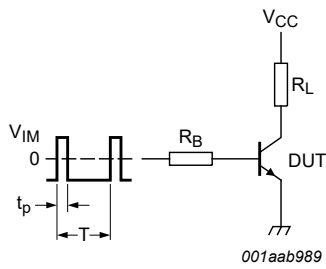


Fig. 12. DC current gain as a function of collector current; typical values



$V_{IM} = -6 \text{ to } +8 \text{ V}$ ;  $V_{CC} = 250 \text{ V}$ ;  $t_p = 20 \text{ } \mu\text{s}$ ;  $\delta = \frac{t_p}{T} = 0.01$   
 $R_B$  and  $R_L$  calculated from  $I_{Con}$  and  $I_{Bon}$  requirements.

Fig. 13. Test circuit for resistive load switching

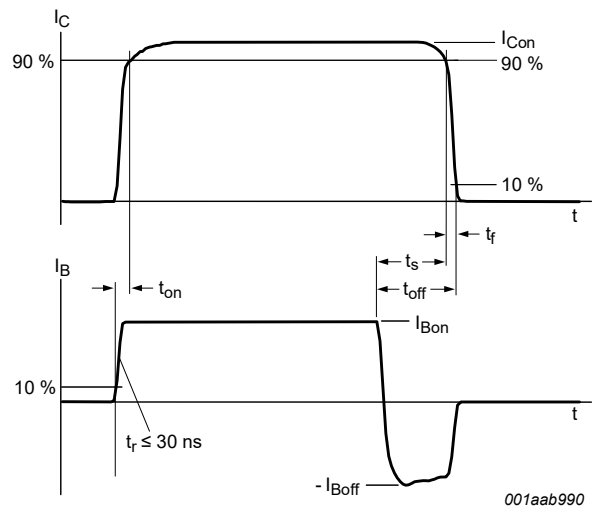
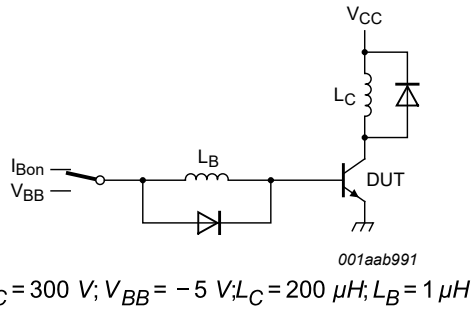
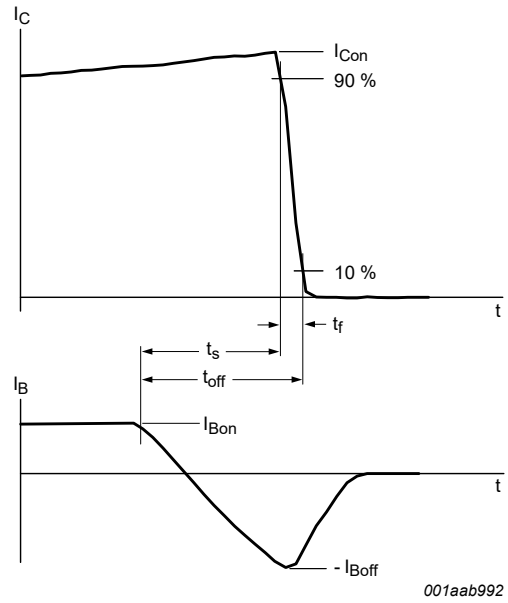


Fig. 14. Switching times waveforms for resistive load



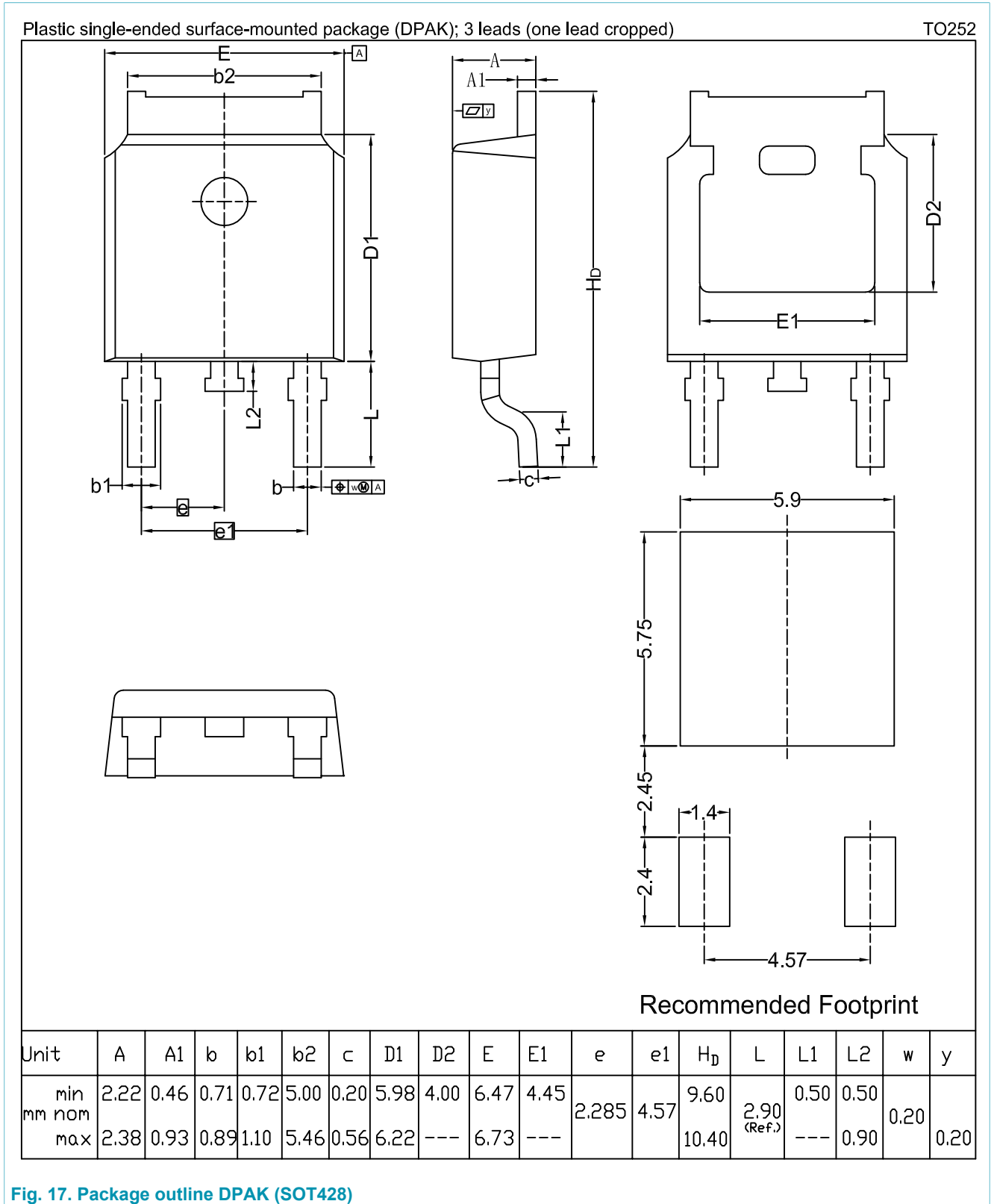


**Fig. 15. Test circuit for inductive load switching**



**Fig. 16. Switching times waveforms for inductive load**

**11. Package outline**



**Fig. 17. Package outline DPAK (SOT428)**

## 12. Legal information

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